

ABSTRACT OF THE DISCLOSURE

An entirely molded semiconductor apparatus in which a flexible sheet having a conductive pattern is employed as a supporting substrate and semiconductor elements are assembled thereon has been developed, wherein such a semiconductor apparatus has various problems by which no multi-layered connection structure is enabled, and warping of insulation resin sheets becomes remarkable in the fabrication process. Since a conductive plated layer 4 is formed after through holes 21 are formed in the insulation resin 2 by using an insulation resin sheet 1 overcoated on a single side of the conductive layer 3 with insulation resin 2, a multi-layer connection structure can be achieved by the second conductive path layer 6 which is connected, in multi layers, to the first conductive path layer 5 formed by etching the conductive plated layer 4. Further, since semiconductor elements 7 are adhered to and fixed at the overcoating resin 8 that covers the first conductive path layer 5, the first conductive path layer 5 is finely patterned, and routing thereof can be made free. Further, since the second conductive layer 4 that has been formed to be thick can be thinly etched, the second conductive path layers 6 can be finely patterned.